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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

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Attn: PCT Branch

H3/PRE-AMDT
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5/10/02

Application No. US National Stage of PCT/JP00/02098

Filed: August 10, 2001

Docket No.: 110345

For: MODIFICATION METHOD OF SURFACE LAYER OF MOLDED RESIN ARTICLE, AND MODIFICATION APPARATUS OF SURFACE LAYER OF MOLDED RESIN ARTICLE

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, and after entry of the Annexes to the IPER, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 13, 14, 19, 20, 24-26, 30, 32, 34, 36, 38 and 40-45 as follows:

13. (Amended) The modification method of the resin surface layer

according to claim 5 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the molded resin article; and

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in order to allow the deposited organic compound to penetrate/disperse from the surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which is equal to or higher than a glass transition temperature of the resin and which does not exceed the thermal decomposition temperature of the organic compound and/or the resin.

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